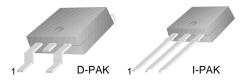


## KSH30/30C

### **General Purpose Amplifier Low Speed Switching Applications**

- Lead Formed for Surface Mount Application (No Suffix)
  Straight Lead (I-PAK, "- I" Suffix)
- Electrically Similar to Popular TIP30 and TIP30C



1.Base 2.Collector 3.Emitter

## **PNP Epitaxial Silicon Transistor**

### Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{CBO}$	Collector-Base Voltage		
	: KSH30	- 40	V
	: KSH30C	- 100	V
V <sub>CEO</sub>	Collector-Emitter Voltage		
	: KSH30	- 40	V
	: KSH30C	- 100	V
V <sub>EBO</sub>	Emitter-Base Voltage	- 5	V
I <sub>C</sub>	Collector Current (DC)	- 1	Α
I <sub>CP</sub>	Collector Current (Pulse)	- 3	Α
I <sub>B</sub>	Base Current	- 0.4	Α
P <sub>C</sub>	Collector Dissipation (T <sub>C</sub> =25°C)	15	W
	Collector Dissipation (Ta=25°C)	1.56	W
T <sub>J</sub>	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature	- 65 ~ 150	°C

### **Electrical Characteristics** T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
V <sub>CEO</sub> (sus)	Collector-Emitter Sustaining Voltage				
020	: KSH30	$I_C = -30 \text{mA}, I_B = 0$	- 40		V
	: KSH30C		- 100		V
I <sub>CEO</sub>	Collector Cut-off Current				
	: KSH30	$V_{CE} = -40V, I_{B} = 0$		- 50	μΑ
	: KSH30C	$V_{CE} = -60V, I_{B} = 0$		- 50	μΑ
I <sub>CES</sub>	Collector Cut-off Current				
	: KSH30	$V_{CE} = -40V, V_{BE} = 0$		- 20	μΑ
	: KSH30C	$V_{CE} = 100V, V_{BE} = 0$		- 20	μΑ
I <sub>EBO</sub>	Emitter Cut-off Current	$V_{BE} = -5V, I_{C} = 0$		- 1	mA
h <sub>FE</sub>	* DC Current Gain	$V_{CE} = -4V, I_{C} = -0.2A$	40		
		$V_{CE} = -4V, I_{C} = -1A$	15	75	
V <sub>CE</sub> (sat)	* Collector-Emitter Saturation Voltage	I <sub>C</sub> = - 1A, I <sub>B</sub> = - 125mA		- 0.7	V
V <sub>BE</sub> (on)	* Base-Emitter On Voltage	V <sub>CE</sub> = - 4A, I <sub>C</sub> = - 1A		- 1.3	V
f <sub>T</sub>	Current Gain Bandwidth Product	V <sub>CE</sub> = - 10V, I <sub>C</sub> = - 200mA	3		MHz

\* Pulse Test: PW≤300ms, Duty Cycle≤2%

# **Typical Characteristics**

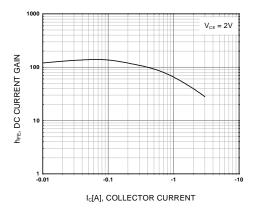


Figure 1. DC current Gain

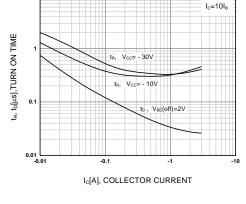


Figure 2. Turn On Time

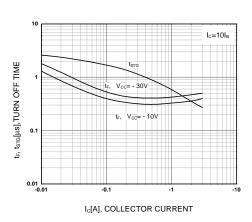


Figure 3. Turn Off Time

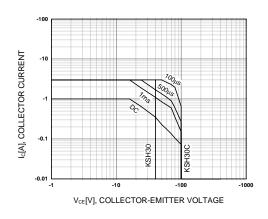


Figure 4. Safe Operating Area

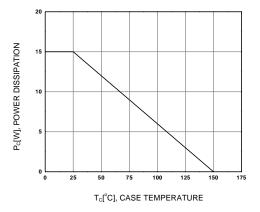
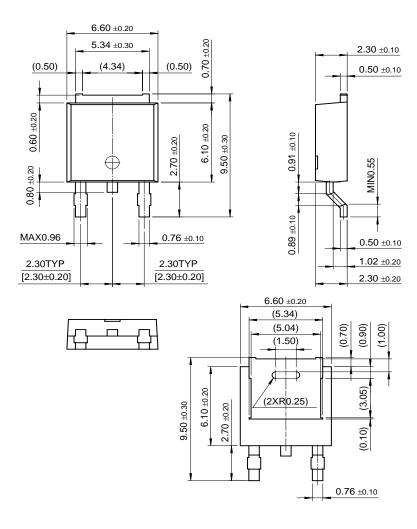


Figure 5. Power Derating

## **Package Dimensions**

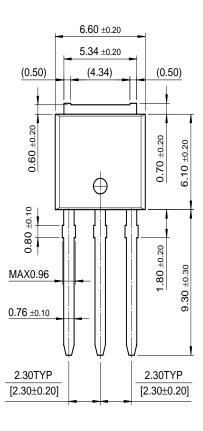
## D-PAK

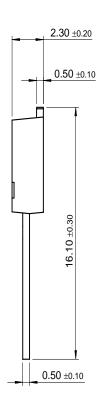


Dimensions in Millimeters

# Package Dimensions (Continued)

## I-PAK







Dimensions in Millimeters

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E <sup>2</sup> CMOS™	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	$I^2C^{TM}$	$OCX^{TM}$	RapidConfigure™	UHC™
Across the board. Around the world.™		OCXPro™	RapidConnect™	UltraFET <sup>®</sup>
The Power Franchise™		OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	VCX <sup>TM</sup>
Programmable Active Droop™		OPTOPLANAR™	SMART START™	

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